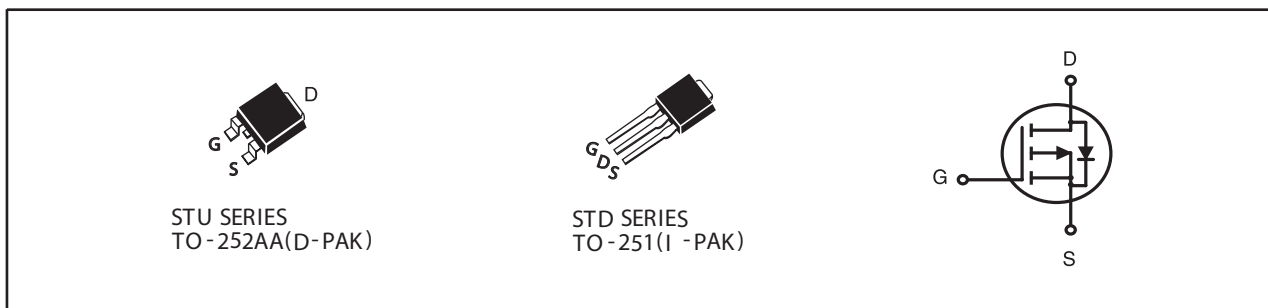


**P-Channel Logic Level Enhancement Mode Field Effect Transistor**

PRODUCT SUMMARY		
VDSS	ID	RDS(ON) (mΩ) Max
-60V	-20A	53 @ VGS=-10V
		80 @ VGS=-4.5V

FEATURES

- Super high dense cell design for low RDS(ON).
- Rugged and reliable.
- TO-252 and TO-251 Package.

**ABSOLUTE MAXIMUM RATINGS (T_C=25°C unless otherwise noted)**

Symbol	Parameter	Limit	Units
V _{DS}	Drain-Source Voltage	-60	V
V _{GS}	Gate-Source Voltage	±20	V
I _D	Drain Current-Continuous	T _C =25°C	-20
		T _C =70°C	-16
I _{DM}	-Pulsed ^a	-60	A
E _{AS}	Single Pulse Avalanche Energy ^c	156	mJ
P _D	Maximum Power Dissipation	T _C =25°C	42
		T _C =70°C	27
T _J , T _{STG}	Operating Junction and Storage Temperature Range	-55 to 150	°C

THERMAL CHARACTERISTICS

R _{θ JC}	Thermal Resistance, Junction-to-Case	3	°C/W
R _{θ JA}	Thermal Resistance, Junction-to-Ambient	50	°C/W

STU/D609S

Ver 1.1

ELECTRICAL CHARACTERISTICS (T_C=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
OFF CHARACTERISTICS						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =-250uA	-60			V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =-48V , V _{GS} =0V			1	uA
I _{GSS}	Gate-Body Leakage Current	V _{GS} = ±20V , V _{DS} =0V			±100	nA
ON CHARACTERISTICS						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =-250uA	-2	-2.7	-4	V
R _{DS(ON)}	Drain-Source On-State Resistance	V _{GS} =-10V , I _D =-10A		42	53	m ohm
		V _{GS} =-4.5V , I _D =-8.5A		59	80	m ohm
g _{FS}	Forward Transconductance	V _{DS} =-10V , I _D =-10A		32		S
DYNAMIC CHARACTERISTICS ^b						
C _{ISS}	Input Capacitance	V _{DS} =-25V, V _{GS} =0V f=1.0MHz		2420		pF
C _{OSS}	Output Capacitance			144		pF
C _{RSS}	Reverse Transfer Capacitance			107		pF
SWITCHING CHARACTERISTICS ^b						
t _{D(ON)}	Turn-On Delay Time	V _{DD} =-30V I _D =-1.0A V _{GS} =-10V R _{GEN} = 6 ohm		54		ns
t _r	Rise Time			33		ns
t _{D(OFF)}	Turn-Off Delay Time			120		ns
t _f	Fall Time			18		ns
Q _g	Total Gate Charge	V _{DS} =-30V, I _D =-10A, V _{GS} =-10V		43		nC
		V _{DS} =-30V, I _D =-10A, V _{GS} =-4.5V		20		nC
Q _{gs}	Gate-Source Charge	V _{DS} =-30V, I _D =-10A, V _{GS} =-10V		7		nC
Q _{gd}	Gate-Drain Charge			11.2		nC
DRAIN-SOURCE DIODE CHARACTERISTICS						
V _{SD}	Diode Forward Voltage	V _{GS} =0V, I _S = -2A		-0.78	-1.3	V

Notes

- a. Pulse Test: Pulse Width ≤ 300us, Duty Cycle ≤ 2%.
 b. Guaranteed by design, not subject to production testing.
 c. Starting T_J=25°C, L=0.5mH, V_{DD} = 30V .(See Figure13)

Jun,22,2012

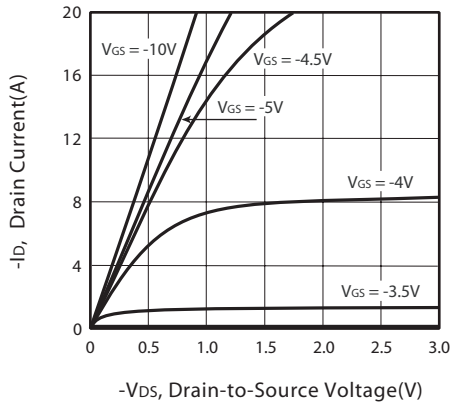


Figure 1. Output Characteristics

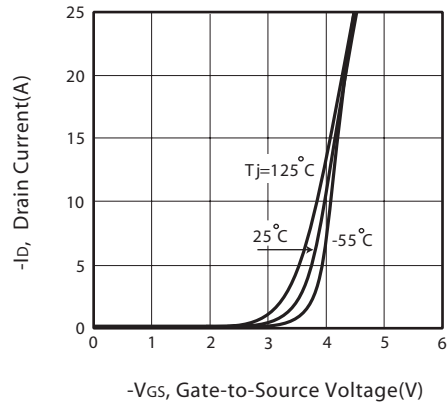


Figure 2. Transfer Characteristics

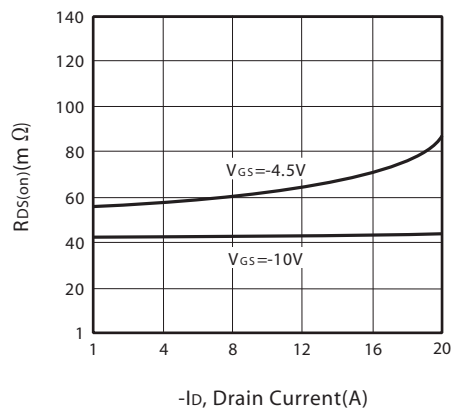


Figure 3. On-Resistance vs. Drain Current and Gate Voltage

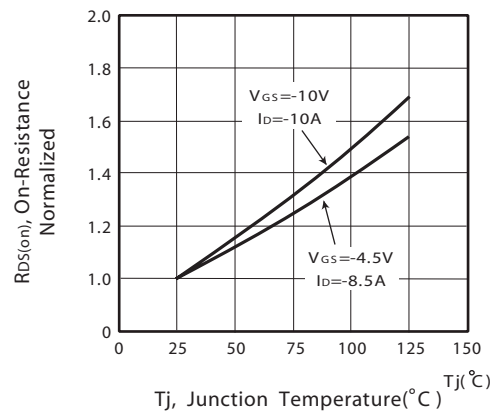


Figure 4. On-Resistance Variation with Drain Current and Temperature

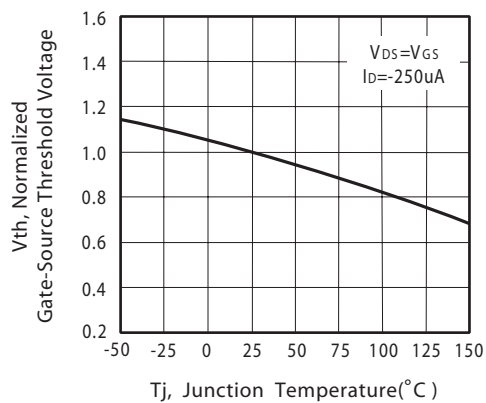


Figure 5. Gate Threshold Variation with Temperature

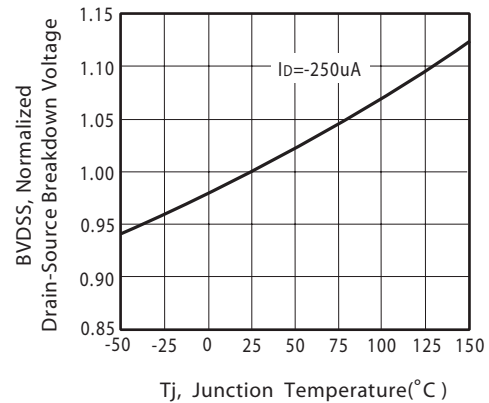


Figure 6. Breakdown Voltage Variation with Temperature

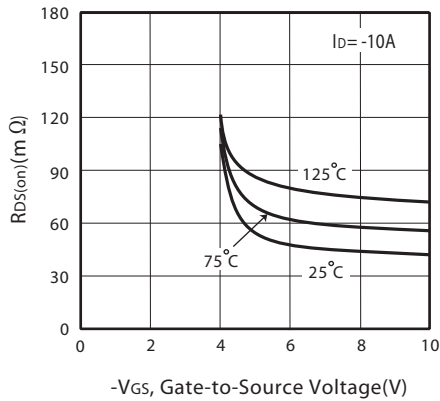


Figure 7. On-Resistance vs. Gate-Source Voltage

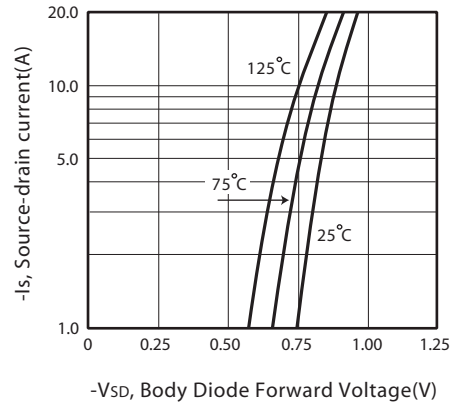


Figure 8. Body Diode Forward Voltage Variation with Source Current

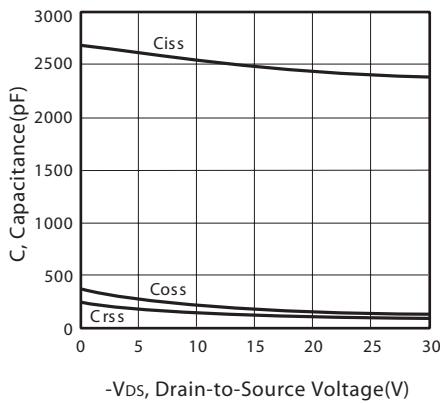


Figure 9. Capacitance

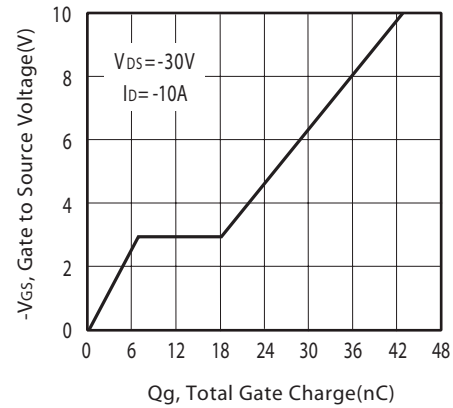


Figure 10. Gate Charge

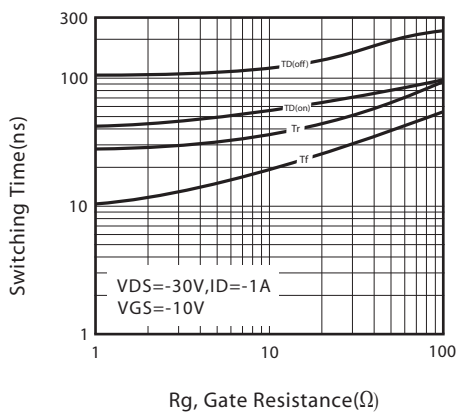


Figure 11. switching characteristics

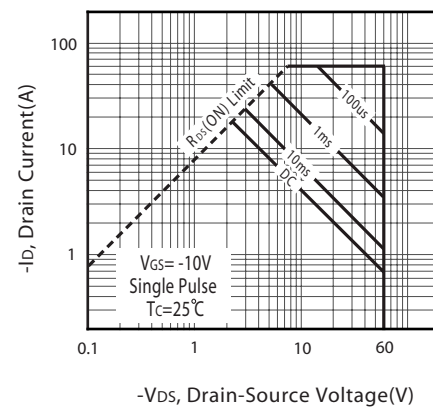
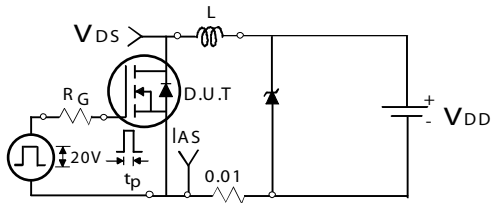
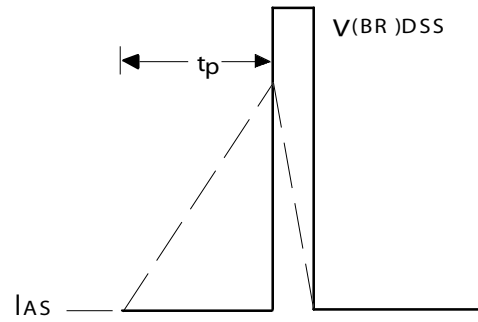


Figure 12. Maximum Safe Operating Area



Unclamped Inductive Test Circuit

Figure 13a.



Unclamped Inductive Waveforms

Figure 13b.

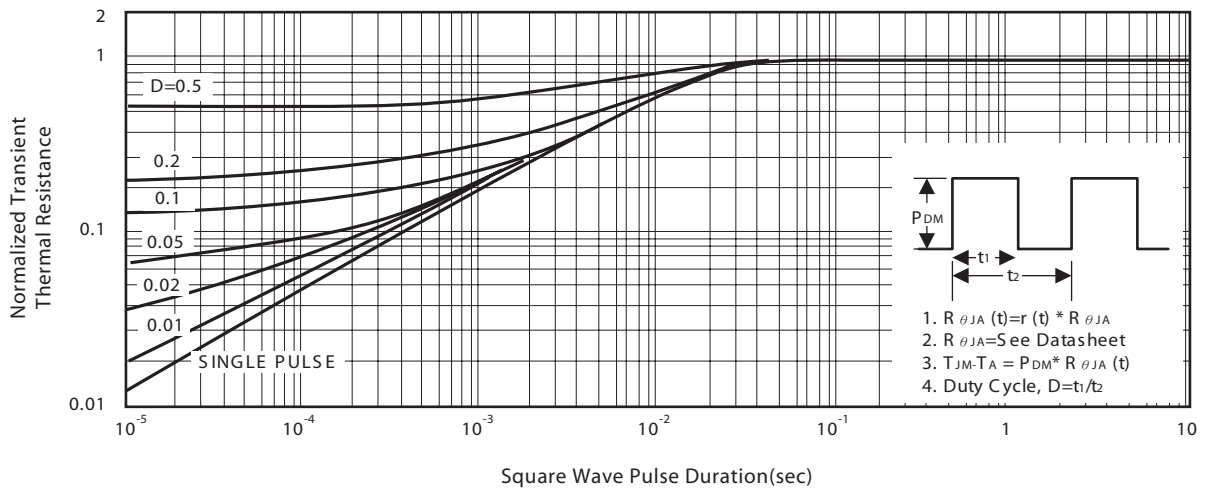
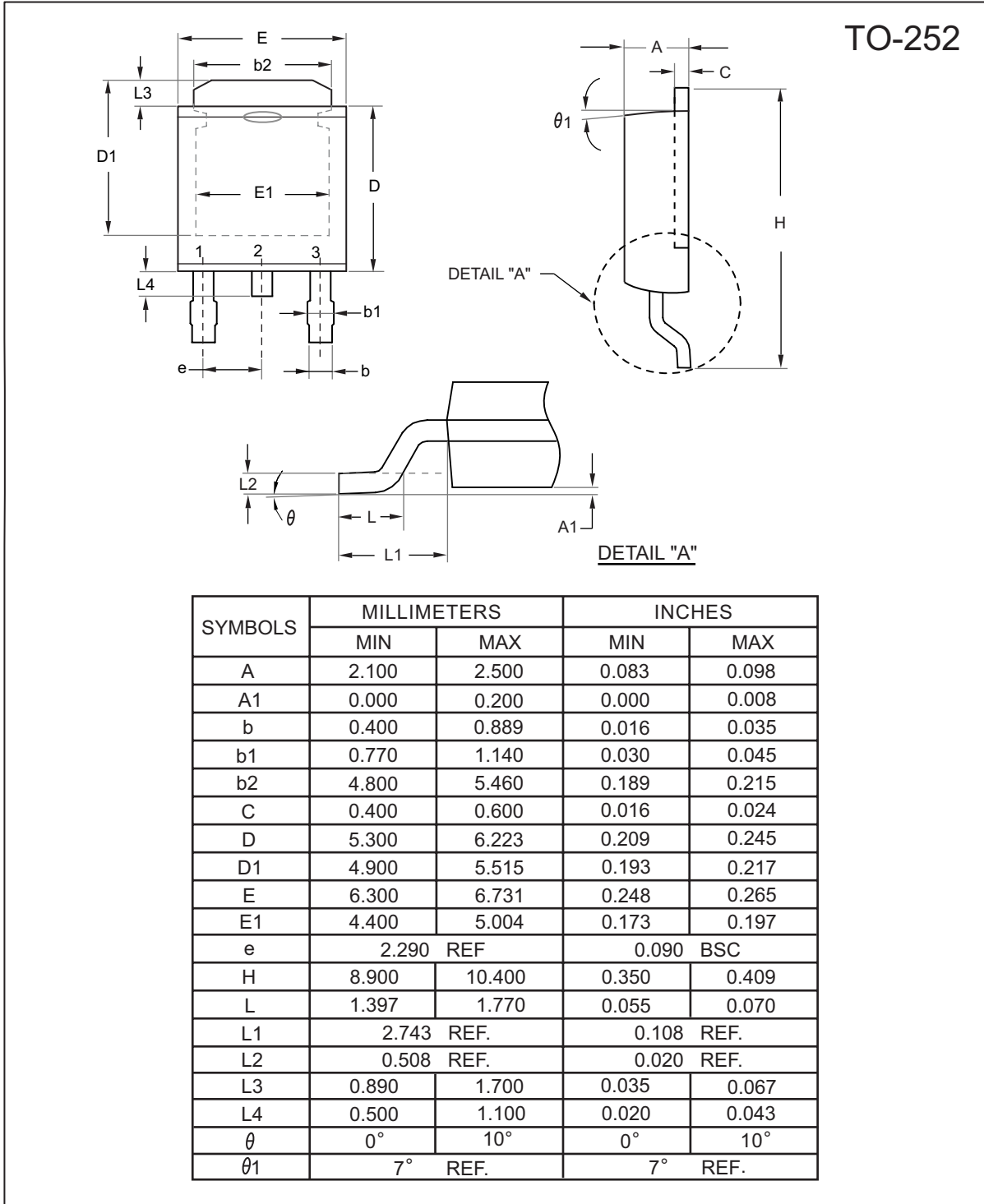
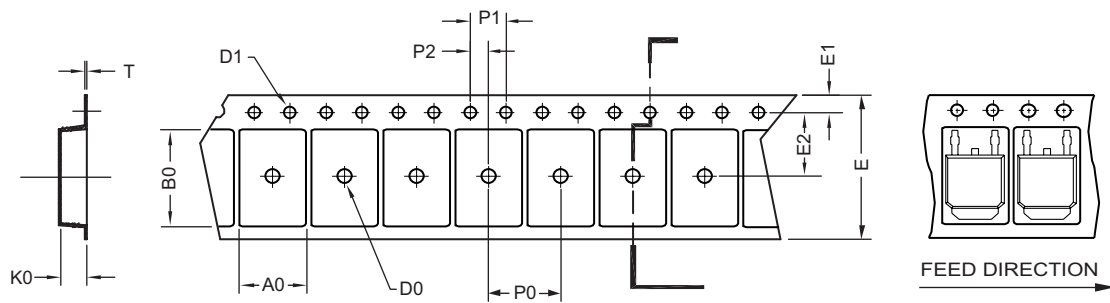


Figure 14. Normalized Thermal Transient Impedance Curve



TO-252 Tape and Reel Data

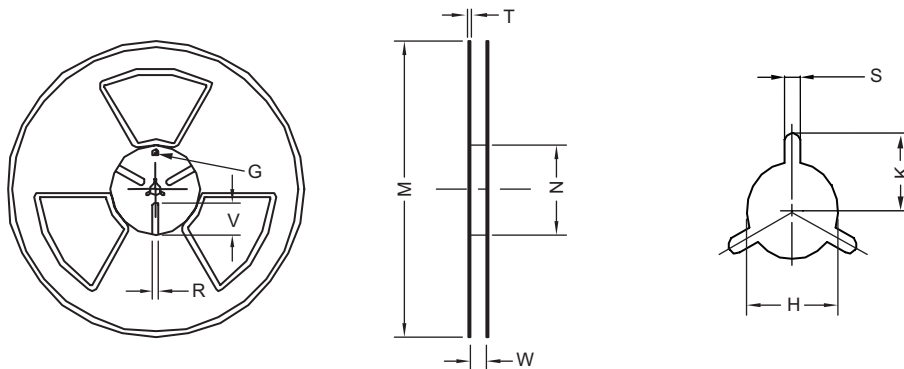
TO-252 Carrier Tape



UNIT:mm

PACKAGE	A0	B0	K0	D0	D1	E	E1	E2	P0	P1	P2	T
TO-252 (16 mm)	6.96 ±0.1	10.49 ±0.1	2.79 ±0.1	φ 2	φ 1.5 + 0.1 - 0	16.0 ±0.3	1.75 ±0.1	7.5 ±0.15	8.0 ±0.1	4.0 ±0.1	2.0 ±0.15	0.3 ±0.05

TO-252 Reel



UNIT:mm

TAPE SIZE	REEL SIZE	M	N	W	T	H	K	S	G	R	V
16 mm	φ 330	φ 330 ± 0.5	φ 97 ± 1.0	17.0 + 1.5 - 0	2.2	φ 13.0 + 0.5 - 0.2	10.6	2.0 ±0.5	---	---	---